

CD4510B, CD4516B Types

CMOS Presettable Up/Down Counters

High-Voltage Types (20-Volt Rating)

CD4510B — — — BCD Type

CD4516B — — — Binary Type

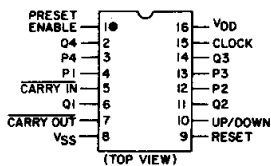
■ CD4510B Presettable BCD Up/Down Counter and the CD4516 Presettable Binary Up/Down Counter consist of four synchronously clocked D-type flip-flops (with a gating structure to provide T-type flip-flop capability) connected as counters. These counters can be cleared by a high level on the RESET line, and can be preset to any binary number present on the jam inputs by a high level on the PRESET ENABLE line. The CD4510B will count out of non-BCD counter states in a maximum of two clock pulses in the up mode, and a maximum of four clock pulses in the down mode.

If the CARRY-IN input is held low, the counter advances up or down on each positive-going clock transition. Synchronous cascading is accomplished by connecting all clock inputs in parallel and connecting the CARRY-OUT of a less significant stage to the CARRY-IN of a more significant stage.

The CD4510B and CD4516B can be cascaded in the ripple mode by connecting the CARRY-OUT to the clock of the next stage. If the UP/DOWN input changes during a terminal count, the CARRY-OUT must be gated with the clock, and the UP/DOWN input must change while the clock is high. This method provides a clean clock signal to the subsequent counting stage. (See Fig. 15).

These devices are similar to types MC14510 and MC14516.

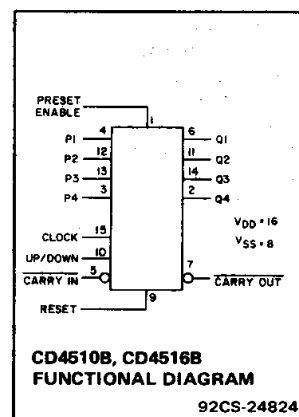
The CD4510B and CD4516B Series types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline package (NSR suffix), and in chip form (H suffix).



92CS-27015
CD4510B, CD4516B
TERMINAL ASSIGNMENT

Features:

- Medium-speed operation --
 $f_{CL} = 8 \text{ MHz typ. at } 10 \text{ V}$
- Synchronous internal carry propagation
- Reset and Preset capability
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized symmetrical output characteristics
- Maximum input current of $1 \mu\text{A}$ at 18 V over full package temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range):
1 V at $V_{DD} = 5 \text{ V}$
2 V at $V_{DD} = 10 \text{ V}$
2.5 V at $V_{DD} = 15 \text{ V}$
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Up/Down difference counting
- Multistage synchronous counting
- Multistage ripple counting
- Synchronous frequency dividers

OPERATING CONDITIONS AT $T_A = 25^\circ\text{C}$, Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

Characteristic	V_{DD}	Min.	Max.	Units
Supply Voltage Range (At $T_A = \text{Full Package-Temperature Range}$)		3	18	V
Clock Pulse Width, t_W	5	150	—	ns
	10	75	—	ns
	15	60	—	ns
Clock Input Frequency, f_{CL}	5	—	2	MHz
	10	—	4	MHz
	15	—	5.5	MHz
Preset Enable or Reset Removal Time [●]	5	150	—	ns
	10	80	—	ns
	15	60	—	ns
Clock Rise and Fall Time, t_{rCL} , t_{fCL} *	5	—	15	μs
	10	—	5	μs
	15	—	5	μs
Carry-In Setup Time, t_S	5	130	—	ns
	10	60	—	ns
	15	45	—	ns
Up-Down Setup Time, t_S	5	360	—	ns
	10	160	—	ns
	15	110	—	ns
Preset Enable or Reset Pulse Width, t_W	5	220	—	ns
	10	100	—	ns
	15	75	—	ns

[●]Time required after the falling edge of the reset or preset enable inputs before the rising edge of the clock will trigger the counter (similar to setup time).

*If more than one unit is cascaded in the parallel clocked application, t_{rCL} should be made less than or equal to the sum of the fixed propagation delay at 15 pF and the transition time of the carry output driving stage for the estimated capacitive load.

CD4510B Types

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal) -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to $V_{DD} + 0.5V$

DC INPUT CURRENT, ANY ONE INPUT $\pm 10\text{mA}$

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$ 500mW

For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$ Derate Linearly at $12\text{mW}/^\circ\text{C}$ to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55°C to $+125^\circ\text{C}$

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to $+150^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance $1/16 \pm 1/32$ inch ($1.59 \pm 0.79\text{mm}$) from case for 10s max $+265^\circ\text{C}$

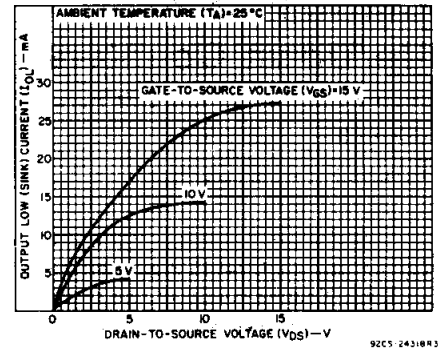


Fig. 1 - Typical output low (sink) current characteristics.

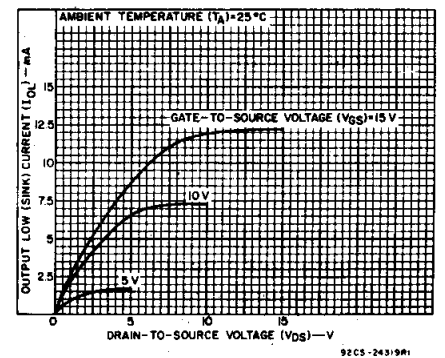


Fig. 2 - Minimum output low (sink) current characteristics.

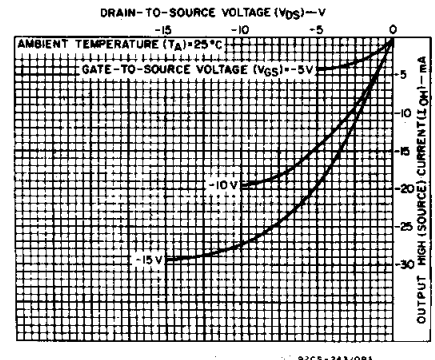


Fig. 4 - Typical output high (source) current characteristics.

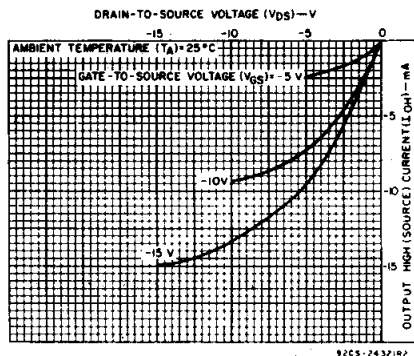


Fig. 5 - Minimum output high (source) current characteristics.

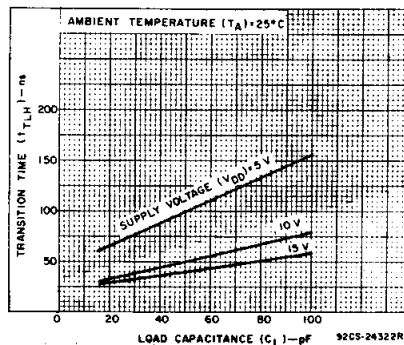


Fig. 6 - Typical transition time vs. load capacitance.

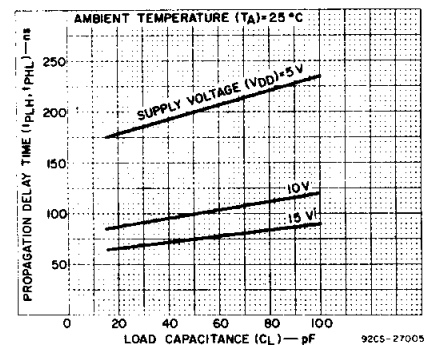


Fig. 7 - Typical propagation delay time vs. load capacitance for clock-to-Q outputs.

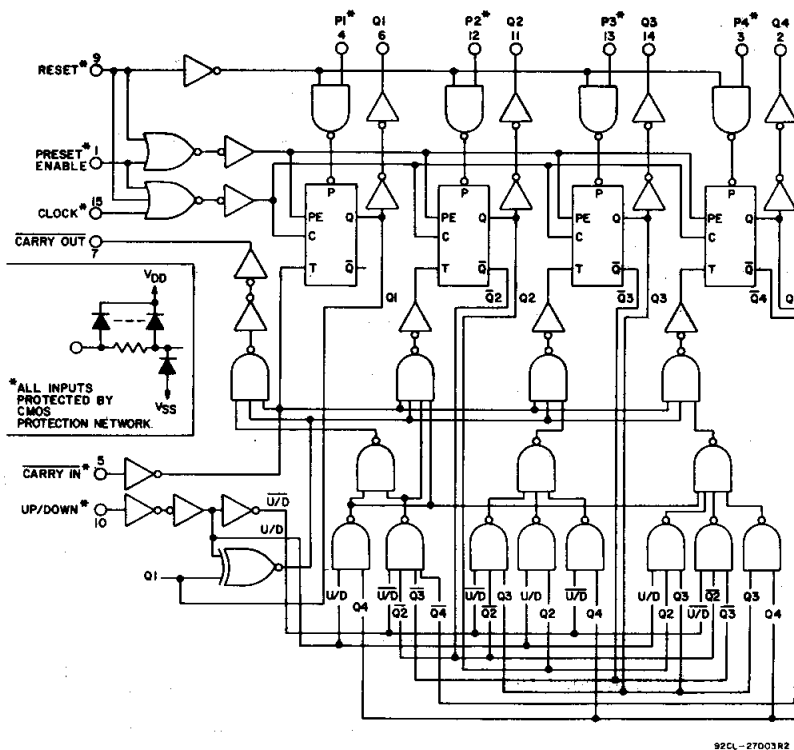


Fig. 3 - Logic Diagram for CD4510B.

CD4510B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	+25							
				-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I _{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	—	0,5	5	4.95				4.95	5	—	V
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage, V _{IL} Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1, 9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, V _{IH} Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1, 9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

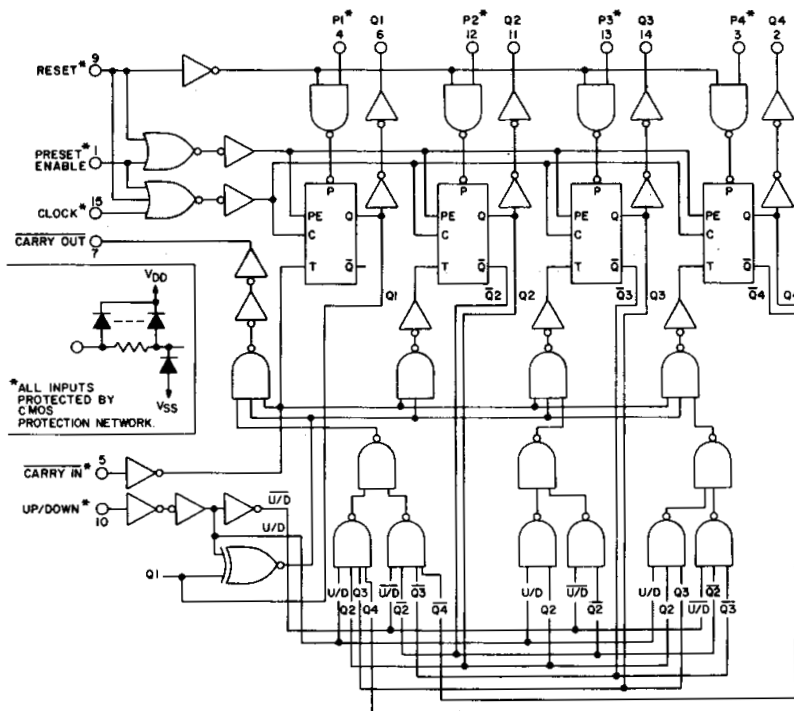


Fig. 10 — Logic Diagram for CD4516B.

92CL-27004R2

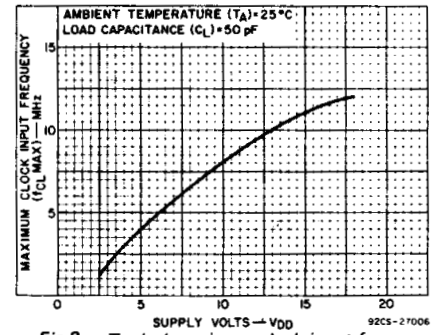


Fig. 8 — Typical maximum clock input frequency vs. supply voltage.

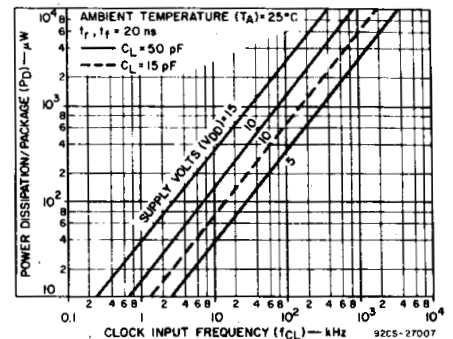


Fig. 9 — Typical dynamic power dissipation vs. frequency.

3

COMMERCIAL CMOS
HIGH VOLTAGE ICs

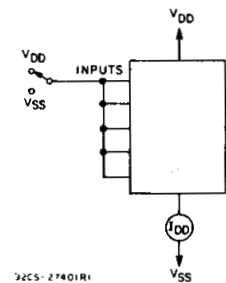


Fig. 11 — Quiescent-device-current test circuit.

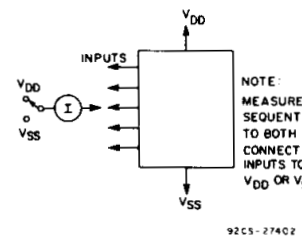


Fig. 12 — Input-current test circuit.

92CS-27402

CD4510B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$,
Input $t_r, t_f = 20\text{ ns}$, $R_L = 200\text{ k}\Omega$

Characteristic	Conditions V_{DD} (V)	Limits All Packages			Units
		Min.	Typ.	Max.	
Propagation Delay Time (t_{PHL}, t_{PLH}):					
Clock-to-Q Output (See Fig. 10)	5 10 15	— — —	200 100 75	400 200 150	ns
Preset or Reset-to-Q Output	5 10 15	— — —	210 105 80	420 210 160	ns
Clock-to-Carry Out	5 10 15	— — —	240 120 90	480 240 180	ns
Carry-In-to-Carry Out	5 10 15	— — —	125 60 50	250 120 100	ns
Preset or Reset-to-Carry Out	5 10 15	— — —	320 160 125	640 320 250	ns
Transition Time (t_{THL}, t_{TLH}) (See Fig. 9)	5 10 15	— — —	100 50 40	200 100 80	ns
Max. Clock Input Frequency (f_{CL})	5 10 15	2 4 5.5	4 8 11	— — —	MHz
Input Capacitance (C_{IN})		—	5	7.5	pF
Set-up Time, t_S Preset Enable to J_n	5 10 15	25 10 10	12 6 5	— — —	ns
Hold times, t_H Clock to Carry-In	5 10 15	60 30 30	30 4 1	— — —	
Clock to Up/Down	5 10 15	30 30 30	10 4 5	— — —	
Preset Enable to J_n	5 10 15	70 40 40	35 20 20	— — —	

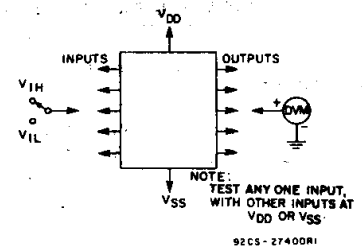


Fig. 13 - Input-voltage test circuit.

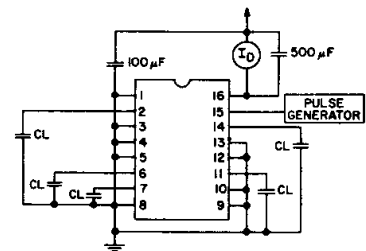


Fig. 14 - Power-dissipation test circuit and input waveform.

CD4510B Types

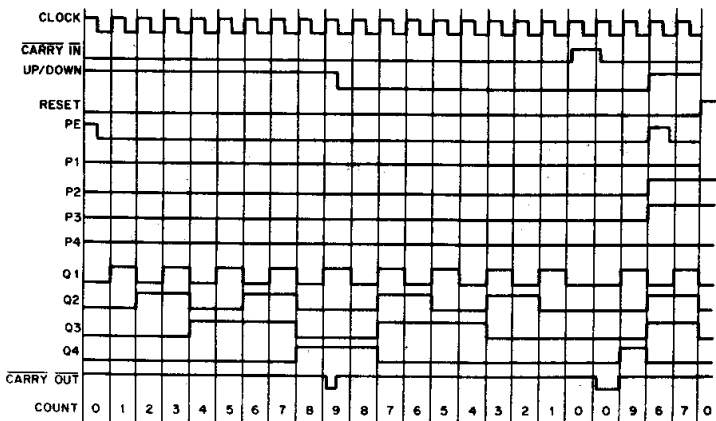


Fig. 15 — Timing Diagram for CD4510B.

92CM-2700B

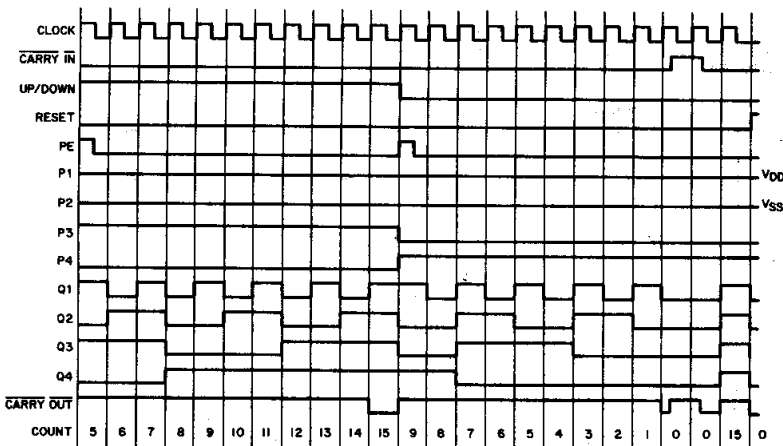
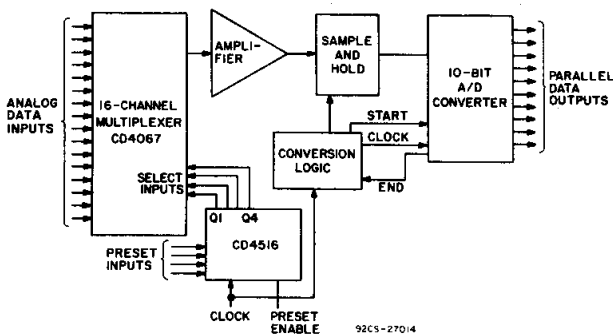


Fig. 16 — Timing diagram for CD4516B.

92CM-27009R1



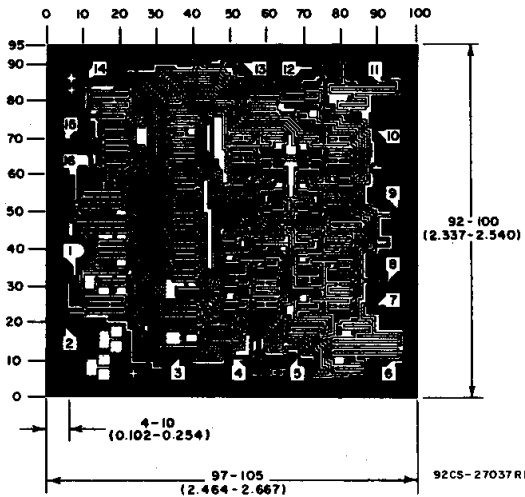
This acquisition system can be operated in the random access mode by jamming in the channel number at the preset inputs, or in the sequential mode by clocking the CD4516B.

Fig. 17 — Typical 16-channel, 10-bit data acquisition system.

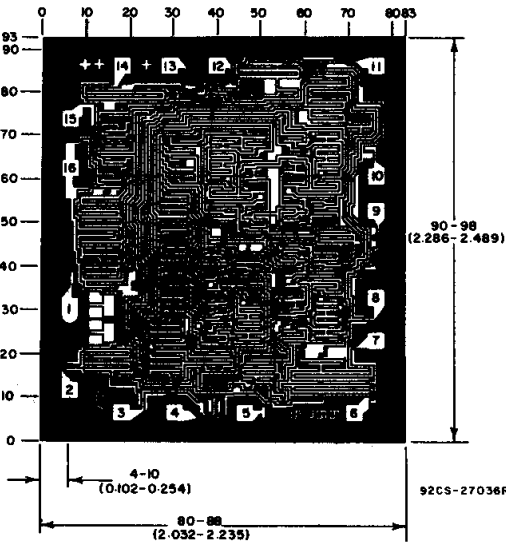
CL	CI	U/D	PE	R	ACTION
X	1	X	0	0	NO COUNT
0	0	1	0	0	COUNT UP
0	0	0	0	0	COUNT DOWN
X	X	X	1	0	PRESET
X	X	X	X	1	RESET

X = DON'T CARE

TRUTH TABLE



Dimensions and Pad Layout for CD4510BH.

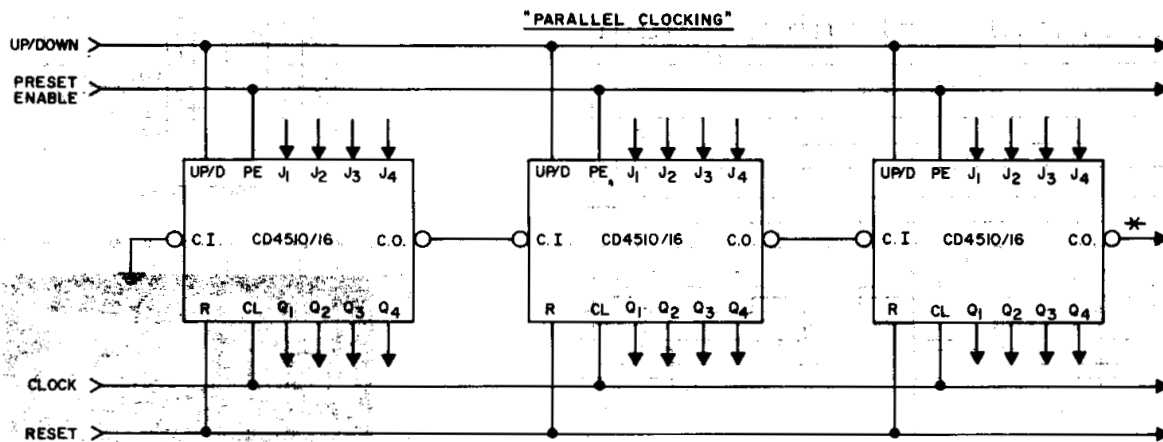


Dimensions and Pad Layout for CD4516BH.

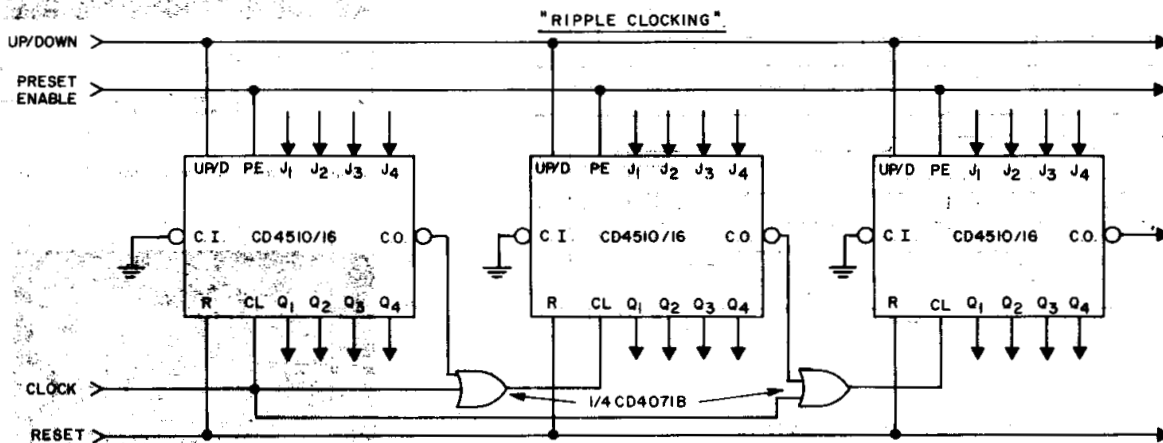
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

3
COMMERCIAL CMOS
HIGH VOLTAGE ICs

CD4510B Types



* CARRY OUT lines at the 2nd, 3rd, etc., stages may have a negative-going glitch pulse resulting from differential delays of different CD4510/16 IC's. These negative-going glitches do not affect proper CD4510/16 operation. However, if the CARRY OUT signals are used to trigger other edge-sensitive logic devices, such as FF's or counters, the CARRY OUT signals should be gated with the clock signal using a 2-input OR gate such as CD4071B.



RIPPLE CLOCKING MODE:
THE UP/DOWN CONTROL CAN BE CHANGED AT ANY COUNT. THE ONLY RESTRICTION ON CHANGING THE UP/DOWN CONTROL IS THAT THE CLOCK INPUT TO THE FIRST COUNTING STAGE MUST BE "HIGH".

For cascading counters operating in a fixed up-count or down-count mode, the OR gates are not required between stages, and C.O. is connected directly to the CL input of the next stage with CI grounded.

92CL-17194R5

Fig. 18 — Cascading counter packages.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265